

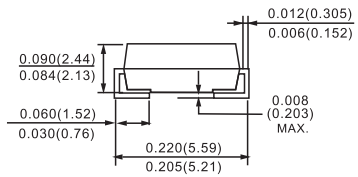
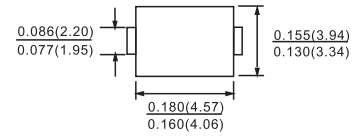
### FEATURES

- Glass passivated device
- Ideal for surface mouted applications
- Low leakage current
- Metallurgically bonded construction
- High temperature soldering:  
250 /10 seconds at terminals

### MECHANICAL DATA

- Case: JEDEC DO-214AA, molded plastic over passivated chip
- Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.006 ounces, 0.02 gram
- Mounting position: Any

DO-214AA(SMB)



Dimensions in inches and (millimeters)

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Symbol	Description	GF2A	GF2B	GF2D	GF2G	GF2J	GF2K	GF2M	Unit	Conditions
<b>VRRM</b>	Max. Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V	
<b>VRMS</b>	Max. RMS Voltage	35	70	140	280	420	560	700	V	
<b>VDC</b>	Max. DC Blocking Voltage	50	100	200	400	600	800	1000	V	
<b>IF(AV)</b>	Max. Average Rectified Current	2.0							A	
<b>IFSM</b>	Peak Forward Surge Current	65							A	
<b>VF</b>	Max. Instantaneous Forward Voltage	1.0							V	IF=2.0A
<b>IR</b>	Max. DC Reverse Current at Rated DC Blocking Voltage	5							μA	TA=25 °C
		30								TA=125 °C
		80								TA=150 °C
<b>CJ</b>	Typical Junction Capacitance	25							pF	
<b>Rθ-JA</b>	Max. Thermal Resistance	53							° C/W	
<b>Rθ-JL</b>		10								
<b>TJ,TSTG</b>	Operating Junction and Storage Temperature Range	-65 to 175							° C	

### RATINGS AND CHARACTERISTIC CURVES GF2A THRU GF2M

#### Typical Characteristics Curves

